

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

MEIER *et al.*

Appl. No.: 10/529,765

Filed: November 3, 2005

For: **Cleaning Device for Cleaning  
Process Gas of a Reflow Soldering  
System**

Confirmation No.: 5840

Art Unit: 1797

Examiner: Pham, Minh Chau Thi

Atty. Docket: 2380.0010000

**Amendment and Reply Under 37 C.F.R. § 1.111**

***Mail Stop Amendment***

Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

Sir:

In reply to the Office Action dated February 20, 2008, (PTO Prosecution File Wrapper Paper No. 20080214), Applicants submit the following Amendment and Remarks.

Amendments to the Abstract begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks and Arguments begin on page 5 of this paper.

It is not believed that extensions of time or fees for net addition of claims are required beyond those that may otherwise be provided for in documents accompanying this paper. However, if additional extensions of time are necessary to prevent abandonment of this application, then such extensions of time are hereby petitioned under 37 C.F.R. § 1.136(a), and any fees required therefor (including fees for net